

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application of: Robert J. Small

Confirmation No. 9378

U.S. Patent No.: 6,777,380  
Application No. 09/903,064

Art Unit: 1751

Issued :August 17, 2004  
Filed: July 10, 2001

Examiner: Gregory E. Webb

For: **METHOD OF CHEMICALLY  
MECHANICALLY POLISHING SUBSTRATES**

Atty No.: 060937-0091-US

U.S. Patent and Trademark Office  
Randolph Building  
401 Dulaney Street  
Alexandria, Virginia 22314

Sir:

**SUBMISSION OF REVOCATION OF ORIGINAL POWER OF ATTORNEY  
AND GRANT OF NEW POWER OF ATTORNEY**

Enclosed is a copy of the Revocation of Original Power of Attorney and Grant of New Power of Attorney by the Assignee, EKC Technology, Inc. Assignee directs the Patent and Trademark Office to send all future correspondence to:


**CUSTOMER NO. 009629  
MORGAN, LEWIS & BOCKIUS LLP  
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Tel. 202-739-3000**

If there is any fee due in connection with the filing of this Submission, please charge the fee to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310.

Respectfully submitted,

January 28 2009

By:

  
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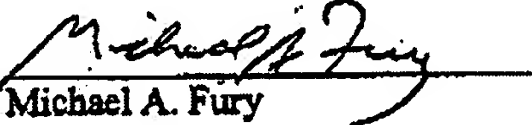
## REVOCATION AND POWER OF ATTORNEY

Commissioner for Patents  
P. O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

EKC Technology, Inc., owner of the entire right, title and interest in, to and under the inventions described and claimed in the patent applications identified in the attached Schedule A, hereby revokes all previous powers of attorney and appoints Morgan, Lewis & Bockius LLP, Customer Number 009629, and each of them, its attorneys, to prosecute each of these patent applications, and to transact all business in the Patent and Trademark Office connected therewith.

Please direct all future correspondence to Customer No. 009629, Patent Support Unit, Morgan, Lewis & Bockius LLP, 1111 Pennsylvania Avenue, N.W., Washington, D.C. 20004, and direct all telephone calls to Morgan, Lewis & Bockius LLP at 202-739-3000.

|                            |   |
|----------------------------|---|
| Assignee:                  | EKC Technology, Inc.  |
| Date: <u>29 March 2004</u> | Signature: <u></u> |
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## Schedule A

| App. No.   | Title  | Inventor(s)           | Filing Date | New Attorney Docket No. | Former Attorney Docket No. |
|------------|--|-----------------------|-------------|-------------------------|----------------------------|
| 09/903,064 | Compositions for Cleaning Organic and Plasma Etched Residues for Semiconductor Devices                               | Small, et al.         | 07/10/2001  | 60937-091-US            | 8317-091-999               |
| 09/874,330 | Method of and Apparatus for Substrate Pre-Treatment  | Maloney, et al.       | 06/06/2001  | 60937-111-US            | 8317-111-999               |
| 09/985,870 | Chemical Mechanical Polishing Compositions   | Small, et al.         | 11/06/2001  | 60937-114-US            | 8317-114-999               |
| 10/421,706 | Oxalic Acid as a Semiaqueous Cleaning Product for Copper and Dielectrics   | Lee, et al.           | 04/24/2003  | 60937-116-US            | 8317-116-999               |
| 10/193,185 | Sulfoxide Pyrrolid(in)one Alkanolamine Cleaner Composition   | Zhou, et al.          | 07/12/2002  | 60937-118-US            | 8317-118-999               |
| 09/876,944 | Method for the Deposition of Materials from Mesomorphous Films   | Vasquez, et al.       | 06/08/2001  | 60937-120-US            | 8317-120-999               |
| 10/007,134 | Post Etch Cleaning Composition for Dual Damascene System   | Payne, et al.         | 12/04/2001  | 60937-123-US            | 8317-123-999               |
| 10/263,701 | Photolytic Conversion Process to Form Patterned Amorphous Film   | Bravo-Vasquez, et al. | 10/04/2002  | 60937-126-US            | 8317-126-999               |
| 09/988,545 | Cleaning Solutions Including Nucleophilic Amine Compound Having Reduction and Oxidation Potential                    | Lee, et al.           | 11/20/2001  | 60937-127-US            | 8317-127-999               |
| 10/060,109 | Method and Compositions for Chemically Treating A Substrate Using Foam Technology                                    | Patel, et al.         | 01/28/2002  | 60937-129-US            | 8317-129-999               |
| 10/135,695 | Cleaning Solution Including Nucleophilic Amine Compound Having Reduction and Oxidation Potential                     | Lee, et al.           | 05/01/2002  | 60937-135-US            | 8317-135-999               |
| 10/448,127 | Fluoride Layer and Removing Same   | Melvin K. Carter      | 05/30/2003  | 60937-137-US            | 8317-137-999               |
| 10/689,657 | Process for the Use of Bis-Choline and Tris-Choline in the Cleaning of Quartz-Coated Polysilicon and Other Materials | Charm, et al.         | 10/22/2003  | 60937-139-US            | 8317-139-999               |
| 10/689,620 | Cleaning Compositions Containing Hydroxylamine Derivatives and Process Using Same for Residue Removal                | Zhou, et al.          | 10/22/2003  | 60937-140-US            | 8317-140-999               |
| 10/689,616 | Composition for Exfoliation Agent to be Used to Remove Resist Residues   | Melvin K. Carter      | 10/22/2003  | 60937-141-US            | 8317-141-999               |
| 60/467,131 | Reducing Oxide Loss When Using Fluoride Chemistries to Remove Post-Etch Residues in Semiconductor Processing         | Lee, et al.           | 05/02/2003  | 60937-142-PR            | 8317-142-888               |

| App. No.   | Title   | Inventor(s)       | Filing Date | New Attorney<br>Docket No. | Former Attorney<br>Docket No. |
|------------|---|-------------------|-------------|----------------------------|-------------------------------|
| 10/630,301 | Method for Depositing Patterned Films of Materials  | Hill, et al.      | 07/30/2003  | 60937-143-US               | 8317-143-999                  |
| 10/716,838 | Methods for the Deposition of Silver and Silver Oxide Films and Patterned Films               | Ruan, et al.      | 11/18/2003  | 60937-147-US               | 8317-147-999                  |
| 10/162,679 | Semiconductor Process Residue Removal Composition and Process                                 | Lee, et al.       | 06/06/2002  | 60937-149-US               | 8317-149-999                  |
| 60/469,826 | System and Method for Cleaning Workpieces Using Supercritical Carbon Dioxide                  | Fury, et al.      | 05/13/2003  | 60937-150-PR               | 8317-150-888                  |
| 10/689,043 | Abrasive-Free Chemical Mechanical Polishing Composition and Polishing Process Containing Same | Yao, et al.       | 10/21/2003  | 60937-151-US               | 8317-151-999                  |
| 10/689,042 | Wet Etch of Titanium-Tungsten Film  | Patel, et al.     | 10/21/2003  | 60937-152-US               | 8317-152-999                  |
| 10/261,197 | Method of Depositing Nanostructured Films with Embedded Nanopores                             | Svensen, et al.   | 09/30/2002  | 60937-153-US               | 8317-153-999                  |
| 10/280,270 | Hydrothermal Treatment of Nanostructured Films  | Mukherjee, et al. | 10/23/2002  | 60937-167-US               | 8317-167-999                  |
| 10/257,469 | Inhibition of Titanium Corrosion  | Daviot, et al.    | 10/11/2002  | 60937-168-US               | 8317-168-999                  |
| 10/401,405 | Chemical Mechanical Polishing Composition and Process   | Small, et al.     | 03/27/2003  | 60937-171-US               | 8317-171-999                  |
| 10/688,900 | Aqueous Phosphoric Acid Compositions for Cleaning Semiconductor Devices                       | Daviot, et al.    | 10/21/2003  | 60937-172-US               | 8317-172-999                  |
| 10/465,906 | Load Lock System for Supercritical Fluid Cleaning   | Fury, et al.      | 06/18/2003  | 60937-175-US               | 8317-175-999                  |
| 10/465,905 | Automated Dense Phase Fluid Cleaning System   | Fury, et al.      | 06/18/2003  | 60937-176-US               | 8317-176-999                  |
| 60/455,439 | Residue Removers for Electrohydrodynamic Cleaning of Semiconductors                           | Robert J. Small   | 03/18/2003  | 60937-178-PR               | 8317-178-888                  |
| 10/361,822 | Free Radical-Forming Activator Attached to Solid and Used to Enhance CMP Formulations         | Scott, et al.     | 02/11/2003  | 60937-179-US               | 8317-179-999                  |
| 10/377,533 | Titanium Carboxylate Films for Use in Semiconductor Processing                                | Hill, et al.      | 02/26/2003  | 60937-182-US               | 8317-182-999                  |
| 10/422,860 | Method of Making Barrier Layers   | Maloney, et al.   | 05/20/2003  | 60937-183-US               | 8317-183-999                  |
| 60/463,739 | Remover Formulation Containing Fluoride for Use During Semiconductor Manufacturing            | Hirasawa, et al.  | 04/18/2003  | 60937-185-PR               | 8317-185-888                  |
| 60/464,125 | Cleaning Composition for Removing Resists and Manufacturing Method of Semiconductor Devices   | Hirasawa, et al.  | 04/21/2003  | 60937-186-PR               | 8317-186-888                  |
| 10/422,212 | Deposition of Permanent Polymer Structures for OLED Fabrication                               | Roman, et al.     | 04/23/2003  | 60937-187-US               | 8317-187-999                  |

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|------------|---|--------------------|-------------|-------------------------|----------------------------|
| 10/442,858 | Semiconductor Process Residue Removal Composition and Process   | Wai Mun Lee        | 05/20/2003  | 60937-189-US            | 8317-189-999               |
| 10/630,300 | Cleaning Compositions and Method of Use Thereof   | Wai Mun Lee        | 07/30/2003  | 60937-194-US            | 8317-194-999               |
| 60/518,337 | Compositions and Methods for Rapidly Removing Overfilled Substrates   | Chelle, et al.     | 11/10/2003  | 60937-200-PR            | 8317-200-888               |
| 10/690,623 | CMP Method for Copper, Tungsten, Titanium, Polysilicon, and Other Substrates Using Organosulfonic Acids as Oxidizers          | Carter, et al.     | 10/23/2003  | 60937-202-US            | 8317-202-999               |
| 60/494,954 | Periodic Acid Compositions for Polishing Nobel Metal/High K Substrates  | Robert J. Small    | 08/14/2003  | 60937-203-PR            | 8317-203-888               |
| 60/509,920 | Cerium Oxide Abrasives for Chemical Mechanical Polishing  | Robert J. Small    | 10/10/2003  | 60937-204-PR            | 8317-204-888               |
| 60/516,736 | Chemical Mechanical Polishing Slurries and Cleaners Containing Salicylic Acid as a Corrosion Inhibitor                        | Carter, et al.     | 11/04/2003  | 60937-206-PR            | 8317-206-888               |
| 60/494,955 | Periodic Acid Compositions for Polishing Ruthenium Substrates   | Robert J. Small    | 08/14/2003  | 60937-207-PR            | 8317-207-888               |
| 10/683,730 | Chemical Mechanical Polishing Compositions and Process  | Small, et al.      | 10/10/2003  | 60937-211-US            | 8317-211-999               |
| 60/514,020 | Alumina Abrasive for Chemical Mechanical Polishing  | Philippe H. Chelle | 10/27/1999  | 60937-213-PR            | 8317-213-888               |
| 60/502,951 | Chemical Mechanical Polishing Slurries and Cleaners Containing Salicylic Acid as a Corrosion Inhibitor                        | Tamilmani, et al.  | 09/16/2003  | 60937-214-PR            | 8317-214-888               |
| 10/665,417 | Compositions for Chemical Mechanical Planarization of Tantalum and Tantalum Nitride   | Small, et al.      | 09/22/2003  | 60937-215-US            | 8317-215-999               |
| 60/526,107 | Alumina Abrasive for Chemical Mechanical Polishing  | Chelle, et al.     | 12/02/2003  | 60937-216-PR            | 8317-216-888               |
| 60/509,922 | Particulate or Particle-Bound Chelating Agents  | Small, et al.      | 10/10/2003  | 60937-217-PR            | 8317-217-888               |
| 10/690,626 | Particulate or Particle-Bound Chelating Agents  | Small, et al.      | 10/23/2003  | 60937-217-US            | 8317-217-999               |
| 60/533,054 | Chemical Mechanical Polishing of STI Features on Semiconductors: Water Polishing with Ceria Slurries                          | Yu, et al.         | 12/30/2003  | 60937-223-PR            | 8317-223-888               |
| 60/511,949 | Removal of Post Etch Residues and Copper Contamination From Low-K Dielectrics Using Supercritical CO2 with Diketone Additives | Jerome Daviot      | 10/14/2003  | 60937-225-PR            | 8317-225-888               |
| 10/694,999 | Method and Apparatus for Substrate Pre-Treatment  | Lee, et al.        | 10/29/2003  | 60937-226-US            | 8317-226-999               |

| App. #     | Title   | Inventor(s)      | Filing Date | New Attorney<br>Bucket No. | Former Attorney<br>Docket No. |
|------------|---|------------------|-------------|----------------------------|-------------------------------|
| 60/515,450 | Method of Chemically Mechanically<br>Polishing Substrates | Brandon S. Scott | 10/30/2003  | 60937-228-PR               | 8317-228-888                  |